



JLHF300V65R62E7DN

L62 PACK module with Trench/Fieldstop IGBT and Emitter Controlled diode and NTC



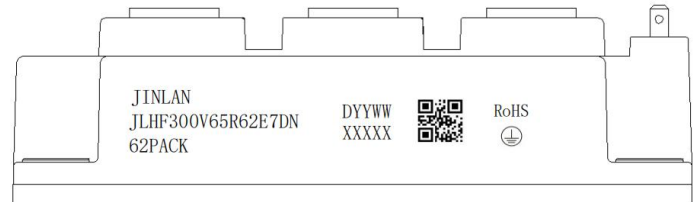
Features

- Low $V_{CE(sat)}$ Trench IGBT technology
- $V_{CE(sat)}$ with positive temperature coefficient
- Maximum junction temperature 175°C
- Low inductance case
- Al_2O_3 substrate with low thermal resistance



L62 Pack

MARKING DIAGRAM



Typical Applications

- Switched mode power supplies
- Servo Drives
- UPS Systems
- Welding inverters

JINLAN

JLHF300V65R62E7DN

YYWW

XXXXX

QR code

= Company Name

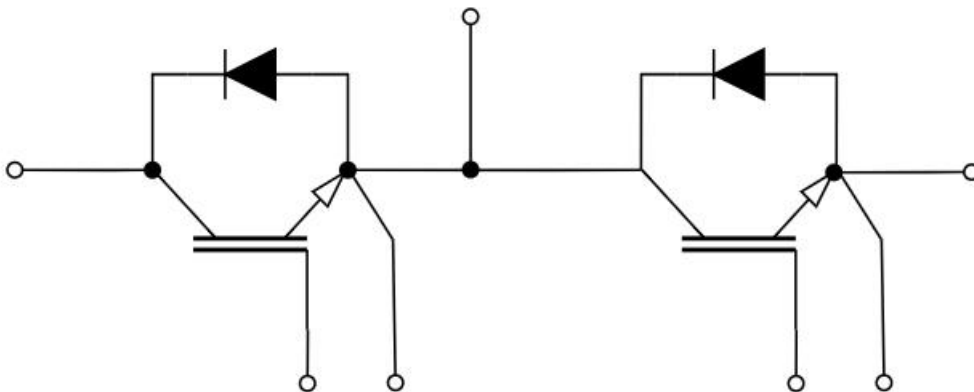
= Specific Device Code

= Year and Work Week Code

= Serial Number

= Custom Assembly Information

Description





Package Insulation coordination

Parameter	Symbol	Note or test condition	Values	Unit
Isolation test voltage	V_{ISOL}	RMS, $f = 50 \text{ Hz}$, $t = 60 \text{ s}$	2.5	kV
Internal isolation		basic insulation(class 1, IEC 61140)	Al_2O_3	
Creepage distance	d_{creep}	terminal to heatsink	29.0	mm
Creepage distance	d_{creep}	terminal to terminal	23.0	mm
Clearance	d_{clear}	terminal to heatsink	23.0	mm
Clearance	d_{clear}	terminal to terminal	11.0	mm
Comparative tracking index (electrical)	CTI		>400	
RTI Elec.	RTI	housing	140	°C

Package Characteristic values

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Stray Inductance	L_{CE}			--	20	--	nH
Module Lead Resistance, Terminal to Chip	$R_{CC'+EE'}$	$T_C=25^\circ\text{C}$, per switch		--	0.7	--	mΩ
Storage temperature	T_{stg}			-40	--	125	°C
Mounting torque for module mounting	M	-Mounting according to valid application note	M6, Screw	3	--	6	Nm
Terminal connection torque	M	-Mounting according to valid application note	M6, Screw	2.5	--	5.0	Nm
Weight	G			--	340	--	g

**IGBT****Absolute Maximum Ratings** ($T_c = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Description	Value	Unit
V_{CES}	Collector-Emitter Voltage	650	V
V_{GES}	Gate-Emitter Voltage	± 30	V
I_{CDC}	Continuous Collector Current @ $T_c = 100^\circ\text{C}$	300	A
I_{CM}	Pulsed Collector Current, $t_p=1\text{ms}$	900	A
P_{tot}	Total power dissipation, $T_c = 25^\circ\text{C}$, $T_{vj\max} = 175^\circ\text{C}$	740	W

Characteristics ($T_c=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Condition		Min	Typ	Max	Unit
V _{CE(sat)}	Collector–Emitter Saturation Voltage	I _C =300 A, V _{GE} = 15 V	T _{vj} = 25 °C	--	1.45	2.10	V
			T _{vj} = 125 °C	--	1.60	--	
			T _{vj} = 175 °C	--	1.65	--	
V _{GE(TH)}	Gate–Emitter Threshold Voltage	I _C =5 mA, V _{CE} =V _{GE}		4.00	4.75	5.50	V
I _{CES}	Collector–Emitter Cutoff Current	V _{GE} = 0 V, V _{CE} = 1200 V		--	--	600	μA
I _{GES}	Gate-Emitter Leakage Current	V _{GE} = ±30 V, V _{CE} = 0 V, T _{vj} = 25 °C		--	--	100	nA
R _{Gint}	Internal Gate Resistance	f=1 MHz		--	0.1	--	Ω
C _{ies}	Input Capacitance	V _{CE} =25 V, V _{GE} =0 V, f=1 MHz		--	16.08	--	nF
C _{oes}	Output Capacitance			--	0.628	--	nF
C _{res}	Reverse Transfer			--	0.116	--	nF
Q _G	Gate Charge	V _{CC} =480V, V _{GE} =15V		--	0.62	--	μC
t _{d(on)}	Turn-On Delay Time	V _{CC} =400V, I _C =300A, V _{GE} =0/15V, R _g =6.2 Ω , Inductive Load T _{vj} = 25 °C		--	170	--	ns
t _r	Rise Time			--	68	--	
t _{d(off)}	Turn-off Delay Time			--	680	--	
t _f	Fall Time			--	105	--	
E _{on}	Turn-On Switching Loss per Pulse			--	6.80	--	mJ
E _{off}	Turn Off Switching Loss per Pulse			--	3.06	--	
t _{d(on)}	Turn-On Delay Time	V _{CC} =400V, I _C =300A, V _{GE} =0/15V, R _g =6.2Ω, Inductive Load T _{vj} = 125 °C		--	TBD	--	ns
t _r	Rise Time			--	TBD	--	
t _{d(off)}	Turn-off Delay Time			--	TBD	--	
t _f	Fall Time			--	TBD	--	
E _{on}	Turn-on Switching Loss per Pulse			--	TBD	--	mJ
E _{off}	Turn Off Switching Loss per Pulse			--	TBD	--	
t _{d(on)}	Turn-On Delay Time	V _{CC} =400V, I _C =300A, V _{GE} =0/15V, R _g =6.2Ω, Inductive Load T _{vj} = 175 °C		--	TBD	--	ns
t _r	Rise Time			--	TBD	--	
t _{d(off)}	Turn-off Delay Time			--	TBD	--	
t _f	Fall Time			--	TBD	--	
E _{on}	Turn-on Switching Loss per Pulse			--	TBD	--	mJ
E _{off}	Turn Off Switching Loss per Pulse			--	TBD	--	
R _{thJC}	Thermal resistance	Junction-to-Case (per IGBT)		--	0.18	-	K/W
T _{vj op}	Temperature under switching conditions			-40		175 ¹⁾	°C

¹⁾ $T_{vj\text{ op}} > 150^\circ\text{C}$ is only allowed for operation at overload conditions. For detailed specifications please refer to AN 2018-14.



Diode

Absolute Maximum Ratings (T_C = 25°C unless otherwise noted)

Symbol	Description	Value	Unit
V _{RRM}	Repetitive Peak Reverse Voltage	650	V
I _F	Diode Continuous Forward Current	300	A
I _{FM}	Diode Maximum Forward Current t _p =1ms	900	A

Characteristics (T_C=25°C unless otherwise noted)

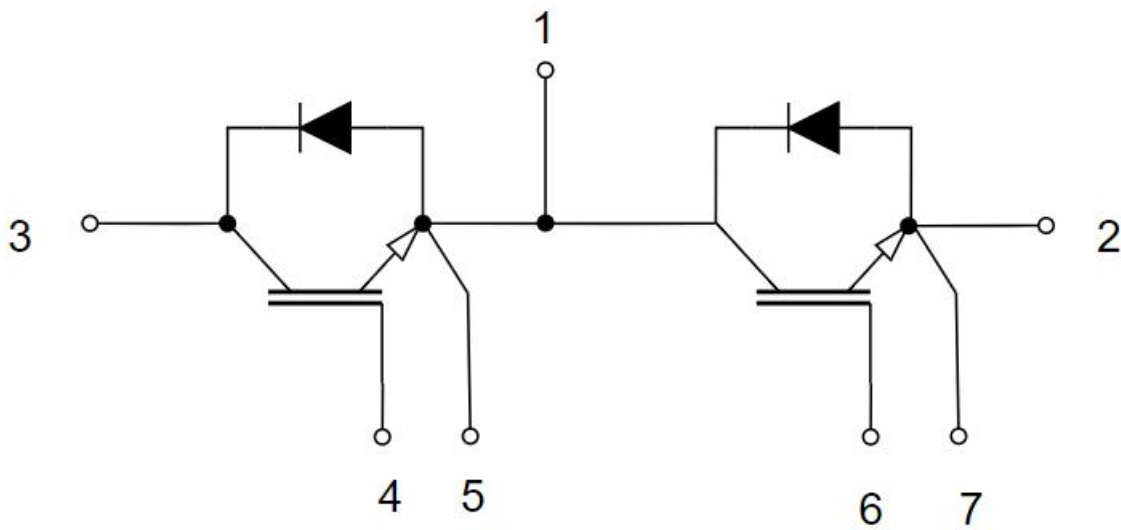
Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
V _F	Diode Forward Voltage	I _F = 300 A, T _{vj} = 25 °C	--	1.70	2.40	V
		I _F = 300 A, T _{vj} = 125 °C	--	1.60	--	
		I _F = 300 A, T _{vj} = 175 °C	--	1.55	--	
T _{rr}	Reverse Recovery Time	I _F =300 A, R _G =6.2 Ω T _{vj} = 25 °C	--	408	--	ns
I _{RM}	Peak Reverse Recovery Current		--	112	--	A
Q _{rr}	Recovered Charge		--	7.17	--	μC
E _{rec}	Reverse Recovery Energy		--	0.81	--	mJ
T _{rr}	Reverse Recovery Time	I _F =300 A, R _G =6.2 Ω T _{vj} = 125 °C	--	TBD	--	ns
I _{RM}	Peak Reverse Recovery Current		--	TBD	--	A
Q _{rr}	Recovered Charge		--	TBD	--	μC
E _{rec}	Reverse Recovery Energy		--	TBD	--	mJ
T _{rr}	Reverse Recovery Time	I _F =300 A, R _G =6.2 Ω T _{vj} = 175 °C	--	TBD	--	ns
I _{RM}	Peak Reverse Recovery Current		--	TBD	--	A
Q _{rr}	Recovered Charge		--	TBD	--	μC
E _{rec}	Reverse Recovery Energy		--	TBD	--	mJ
R _{thJC}	Thermal resistance	Junction-to-Case (per diode)	--	0.36	--	K/W
T _{vj op}	Temperature under switching conditions		-40		175 ²⁾	°C

²⁾T_{vj op} > 150°C is only allowed for operation at overload conditions. For detailed specifications please refer to AN 2018-14.

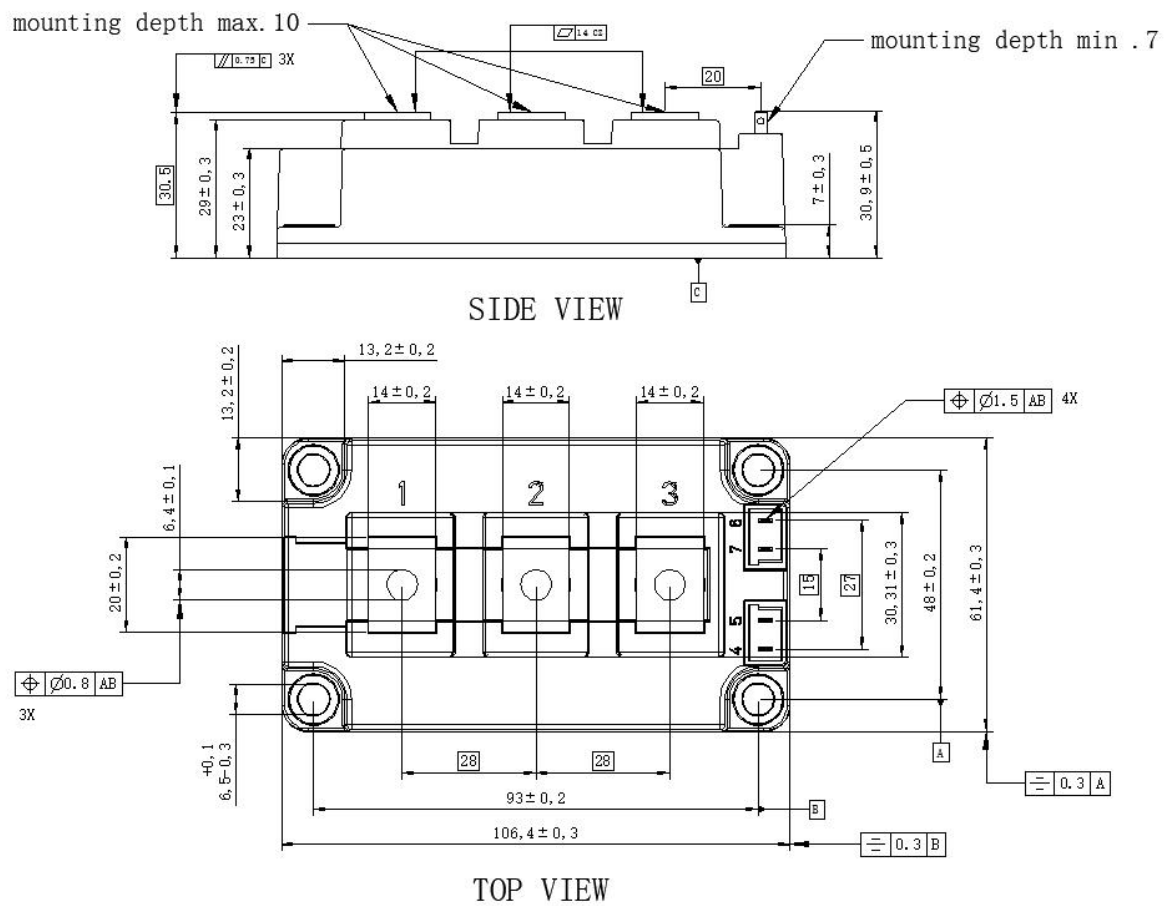
NTC Characteristics (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
R ₂₅	Rated Resistance		--	5.0	--	kΩ
ΔR/R	Deviation of R ₁₀₀	T _C =100 °C, R ₁₀₀ =493.3 Ω	-5	--	5	%
P ₂₅	Power Dissipation		--	--	20.0	mW
B _{25/50}	B-value	R ₂ =R ₂₅ exp[B _{25/50} (1/T ₂ - 1/(298.15K))]	--	3375	--	K
B _{25/80}	B-value	R ₂ =R ₂₅ exp[B _{25/80} (1/T ₂ - 1/(298.15K))]	--	3411	--	K
B _{25/100}	B-value	R ₂ =R ₂₅ exp[B _{25/100} (1/T ₂ - 1/(298.15K))]	--	3433	--	K

CIRCUIT DIAGRAM



PACKAGE DIMENSION





REVISION HISTORY

Document version	Date of release	Description of changes
Rev.00	2024-10-18	Preview



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